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BIPOLAR ANALOG INTEGRATED CIRCUIT UPC2757TB / UPC2758TB

3 V, SUPER MINIMOLD SI MMIC DOWNCONVERTER

FEATURES

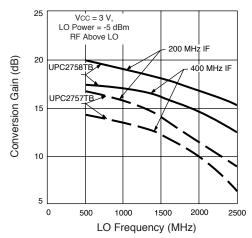
- HIGH-DENSITY SURFACE MOUNTING:
 6 pin super minimold or SOT-363 package
- WIDEBAND OPERATION: RF = 0.1 GHz to 2.0 GHz IF = 20 MHz to 300 MHz
- BUILT-IN POWER SAVE FUNCTION
- SUPPLY VOLTAGE: Vcc = 2.7 TO 3.3 V

DESCRIPTION

The UPC2757TB and UPC2758TB are silicon RFICs manufactured using the NESAT™III process. The devices consist of a mixer, an IF amplifier and an LO buffer amplifier. These devices are suitable as 1st IF downconverters for the receiver stage of cellular and other wireless systems. The UPC2757TB is designed for low power consumption while the UPC2758TB is designed for low distortion. The UPC2757TB/58TB are pin compatible and have comparable performance to the larger UPC2757T/58T, so they are suitable for use as a replacement to help reduce system size. The IC is housed in a 6 pin super minimold or SOT-363 package.

Stringent quality assurance and test procedures ensure the highest reliability and performance.

CONVERSION GAIN vs. LO FREQUENCY



ELECTRICAL CHARACTERISTICS (TA = 25°C, VCC = VPS = 3.0 V, PLO = -10 dBm)

PART NUMBER PACKAGE OUTLINE				UPC2757TB \$06			UPC2758TB S06		
SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	MIN	TYP	MAX	MIN	TYP	MAX	
Icc	Circuit Current, VPS = 3 V VPS = 0.5 V	mA μA	3.7	5.6 0.1	7.7	6.6	11 0.1	14.8	
fRF	RF Operating Frequency Range (The conversion gain at fRF is not more than 3 dB down from the gain at fRF = 800 MHz, fIF = 130 MHz)	GHz	0.1		2.0	0.1		2.0	
fiF	IF Operating Frequency Range (The conversion gain at fir is not more than 3 dB down from the gain at fir = 800 MHz, fir = 130 MHz)	MHz	20		300	20		300	
CG	Conversion Gain ¹ , fRF = 800 MHz, fIF = 130 MHz fRF = 2.0 GHz, fIF = 250 MHz	dB dB	12 10	15 13	18 16	16 14	19 17	22 20	
NF	Noise Figure,	dB dB		10 13	13 16		9 13	12 15	
Psat	Saturated Output Power ² , fre = 800 MHz, fir = 100 MHz fre = 2.0 GHz, fir = 250 MHz	dBm dBm	-11 -11	-3 -8		-7 -7	+1 -4		
P _{1dB}	Output Power at 1dB fRF = 800 MHz compression point fIF = 100 MHz	dBm		-8			-3.5		
OIP3	Output 3rd Order Intercept Point, (SSB) PLO = -10 dBm fRF = 0.8~2.0 GHz, fIF = 100 MHz	dBm		+5			+11		
ISOL	LO Leakage, fLo = 0.8 ~2.0 GHz at RF pin at IF pin	dBm dBm		-35 -23			-30 -15		
RTH (J-A)	Thermal Resistance (Junction to Ambient) Mounted on a 50 x 50 x 1.6 mm epoxy glass PWB	°C/W			325			325	

Notes:

1. PRF = -40 dBm. 2. PRF = -10 dBm.

ABSOLUTE MAXIMUM RATINGS¹ (TA = 25°C)

SYMBOLS	PARAMETERS	UNITS	RATINGS	
VCC, VPS	VPS Supply Voltage		5.5	
Рт	Total Power Dissipation ²	mW	200	
Тор	Operating Temperature	°C	-40 to +85	
Тѕтс	Storage Temperature	°C	-55 to +150	

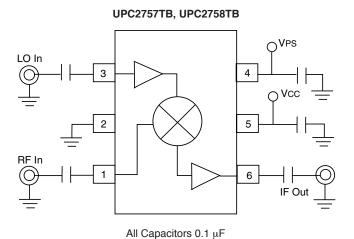
Notes:

- 1. Operation in excess of any one of these parameters may result in permanent damage.
- 2. Mounted on a 50 x 50 x 1.6 mm epoxy glass PWB ($TA = +85^{\circ}C$).

RECOMMENDED OPERATING CONDITIONS

SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
Vcc	Supply Voltage	V	2.7	3.0	3.3
Тор	Operating Temperature	°C	-40	+25	+85
PLO	LO Input Level	dBm	-15	-10	0

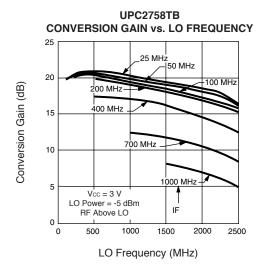
TEST CIRCUIT/BLOCK DIAGRAM

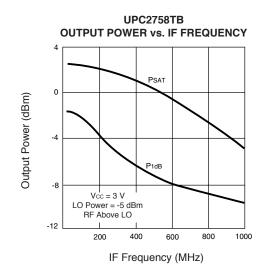


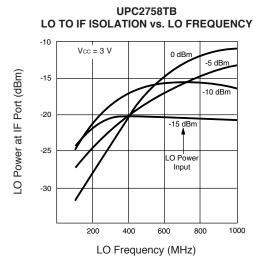
PIN DESCRIPTION

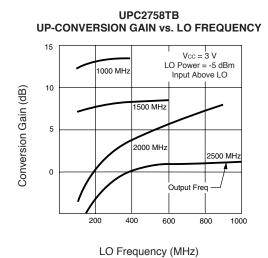
Pin No.	Pin Name	Applied Voltage (V)	Pin Voltage (V)	Description	Internal Equivalent Circuit
1	RFIN	-	1.2	Signal input pin to double balanced mixer. This pin must be coupled to the signal source with a blocking capacitor.	From CO
2	GND	0	_	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible.	
3	LOIN	_	1.3	LO input pin. The LO buffer is designed as a differential amplifier. Recommended input level is -15 to 0 dBm.	Voc Mixer
4	VPS	VCC / GND	_	Power save control pin can control the On/Sleep state with bias as follows: VPS (V) STATE ≥2.5 ON 0 to 0.5 SLEEP Rise time/fall time using this pin is approximately 10 μs.	Vcc Vcc
5	Vcc	2.7 to 3.3	_	Power supply pin. This pin should be externally equipped with a bypass capacitor to minimize ground impedance.	
6	ІГоит	_	1.7	Output of single-ended push-pull IF buffer amplifier. This is an emitter-follower output with low impedance. This pin must be coupled to the next stage with a blocking capacitor.	

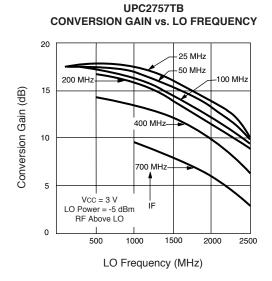
TYPICAL PERFORMANCE CURVES (TA = 25°C)

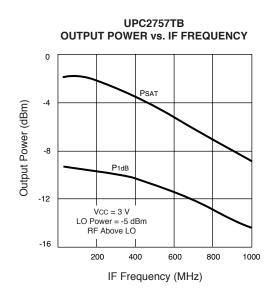






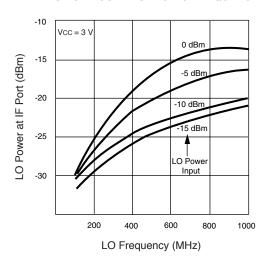




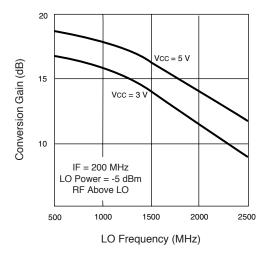


TYPICAL PERFORMANCE CURVES (TA = 25°C)

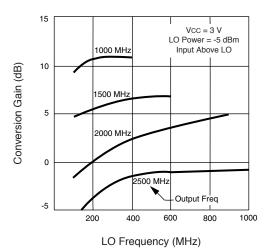
UPC2757TB LO TO IF ISOLATION vs. LO FREQUENCY



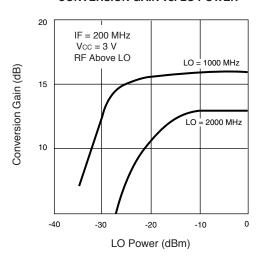
UPC2757TB
CONVERSION GAIN vs. LO FREQUENCY



UPC2757TB UP-CONVERSION GAIN vs. LO FREQUENCY

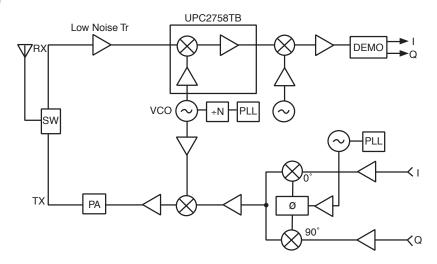


UPC2757TB
CONVERSION GAIN vs. LO POWER



APPLICATION EXAMPLE

Digital Cellular Telephone



ORDERING INFORMATION

PART NUMBER	QTY
UPC2757TB-E3-A	3K/Reel
UPC2758TB-E3-A	3K/Reel

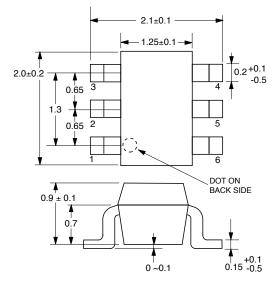
Note:

Embossed Tape, 8 mm wide,

Pins 1, 2, 3 are in tape pull-out direction.

OUTLINE DIMENSIONS

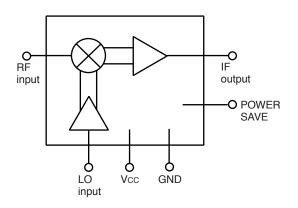
PACKAGE OUTLINE S06



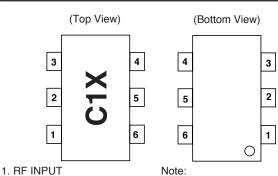
Note:

All dimensions are typical unless otherwise specified.

INTERNAL BLOCK DIAGRAM



LEAD CONNECTIONS



- 2. GND
- 3. LO INPUT
- 4. PS
- 5. Vcc
- 6. IF OUTPUT

Package Markings:

C1X: UPC2757TB C1Y: UPC2758TB